

**Harvatek Surface Mount CHIP LEDs Data Sheet**  
**B2571IRP-A1C000172U1930**  
**Preliminary**

|   |                                     |            |             |
|---|-------------------------------------|------------|-------------|
| Official Product  | HT Part No. B2571IRP-A1C000172U1930 |            |             |
| Tentative Product   | *****                               | *****      | *****       |
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2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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## Product Specifications

| Item                           | Specification  | Material                          | Quantity         |
|--------------------------------|--|-----------------------------------|------------------|
| Peak Wavelength<br>$\lambda_p$ | Typ:850 nm<br>@100mA/ $T_s= 25^\circ\text{C}$ ; Tolerance: $\pm 1$ nm      |                                   |                  |
| Radiant Intensity<br>$I_e$     | Typ:100 mW/sr<br>@100mA/ $T_s= 25^\circ\text{C}$ ; Tolerance: $\pm 10\%$   |                                   |                  |
| Forward Voltage<br>$V_F$       | 1.2-2.0 V<br>@100mA/ $T_s= 25^\circ\text{C}$ ;Tolerance: $\pm 0.1\text{V}$ |                                   |                  |
| Reverse Current<br>$I_R$       | < 10 $\mu\text{A}$<br>@ $V_R = 5$ V  |                                   |                  |
| Resin                          | Clear  | Epoxy                             |                  |
| Carrier tape                   | EIA 481-1A specs   | Conductive black tape             |                  |
| Reel                           | EIA 481-1A specs   | Conductive black                  |                  |
| Label                          | HT standard  | Paper                             |                  |
| Packing bag                    | 250x230mm  | Aluminum laminated bag/ no-zipper | One reel per bag |
| Carton                         | HT standard  | Paper                             | Non-specified    |

**Others:**

Each immediate box consists of 5 reels. The 5 reels may not necessarily have the same lot number or the same bin combinations of  $I_v$ ,  $\lambda_D$  and  $V_f$ . Each reel has a label identifying its specification; the immediate box consists of a product label as well.

Note :This is shipped test conditions

※Remarks: This product should be operated in forward bias. If a reverse voltage is continuously applied to the product, such operation can cause migration resulting in LED damage.

**ATTENTION: Electrostatic Discharge (ESD) protection**



The symbol to the left denotes that ESD precaution is needed. ESD protection for GaP and AlGaAs based chips is necessary even though they are relatively safe in the presence of low static-electric discharge. Parts built with AlInGaP, GaN, or/and InGaN based chips are **STATIC SENSITIVE devices**. ESD precaution must be taken during design and assembly.

If manual work or processing is needed, please ensure the device is adequately protected from ESD during the process.

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## Label Specifications



### ■Harvatek P/N:

**B            257            1            IRP-            A1C            0001            72**

| Product | Package                     | Dice Q'ty | Color    | Current | Series Number | Taping                     |
|---------|-----------------------------|-----------|----------|---------|---------------|----------------------------|
| PCB     | 3.2(L)x1.6(W)x2.55(H)<br>mm | 1:Single  | IR:850nm | 100mA   | X001~XZZZ     | 1. Taping style<br>2. Q'ty |

### ■ Lot No.:

| 1                     | 2        | 3   | 4   | 5  | 6                  | 7        | 8            | 9        | 10       |
|-----------------------|----------|---|---|--|--------------------|----------|--------------|----------|----------|
| <b>E</b>              | <b>1</b> | <b>A</b>  | <b>1</b>  | <b>A</b>   | <b>2</b>           | <b>2</b> | <b>L</b>     | <b>1</b> | <b>2</b> |
| Code 1 2              |          | Code 3  | Code 4  | Code 5   | Code 6             | Code 7   | Code 8       | Code 9   | Code 10  |
|                       |          | Mfg. Year   | Mfg. Month  | Mfg. Date  | Consecutive number |          | Special code |          |          |
| Internal Tracing Code |          | 2020-L<br>2021-M<br>2022-P<br>2023-Q<br>...<br>2026-T<br>2027-V<br>...<br>2030-Y<br>2031-Z<br>... | 1:Jan.<br>2:Feb.<br>...<br>A:Oct.<br>B:Nov.<br>C:Dec. | 1:A<br>2:B<br>3:C<br>...<br>26:Z<br>27:7<br>28:8<br>29:9<br>30:3<br>31:4 | 01~ZZ              |          | 000~ZZZ      |          |          |

|   |                                     |            |             |
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### Absolute Maximum Rating at 25°C

| Symbol          | Parameters            | Ratings    | Units | Notes |
|-----------------|-----------------------|------------|-------|-------|
| I <sub>F</sub>  | Forward Current       | 100        | mA    |       |
| I <sub>FP</sub> | Peak Forward Current  | 1          | A     | 1     |
| V <sub>R</sub>  | Reverse Voltage       | 5          | V     |       |
| T <sub>op</sub> | Operating Temperature | -40 ~ +85  | °C    |       |
| T <sub>st</sub> | Storage Temperature   | -40 ~ +100 | °C    |       |
| T <sub>s</sub>  | Soldering Temperature | 260        | °C    | 2     |

**Notes:**

- I<sub>FP</sub> Conditions--Pulse Width ≤ 100µs and Duty ≤ 1%
- Soldering time ≤ 5 seconds.

### Electro-Optical Characteristics

| Symbol            | Parameters                                    | Test conditions       | Min | Typ  | Max | Units | Notes |
|-------------------|---|-----------------------|-----|------|-----|-------|-------|
| I <sub>e</sub>    | Radiant Intensity                             | I <sub>F</sub> =100mA | 80  | 100  | 130 | mW/sr | 3     |
| λ <sub>P</sub>    | Peak Wavelength                               | I <sub>F</sub> =100mA | -   | 850  | -   | nm    |       |
| Δλ                | Spectral bandwidth at 50% of I <sub>max</sub> | I <sub>F</sub> =100mA | -   | 33   | -   | nm    | 4     |
| V <sub>F</sub>    | Forward Voltage                               | I <sub>F</sub> =100mA | 1.2 | 1.58 | 2.0 | V     | 5     |
| I <sub>R</sub>    | Reverse Current                               | V <sub>R</sub> =5V    | -   | -    | 10  | µA    |       |
| 2θ <sub>1/2</sub> | Angle of Half Intensity (X)                   | I <sub>F</sub> =100mA | -   | 30   | -   | deg   |       |
|                   | Angle of Half Intensity (Y)                   |                       | -   | 30   | -   |       |       |

**Notes:**

- Radiant Intensity (I<sub>e</sub>) Bin:

| Color | Bin Code | Spec. Range   |
|-------|----------|---------------|
| IRP   | HMQ      | 80-90 mW/sr   |
|       | HQU      | 90-100 mW/sr  |
|       | HV       | 100-110 mW/sr |
|       | HW       | 110-120 mW/sr |
|       | HX       | 120-130 mW/sr |

**Notes:**

|   |                                     |            |                       |
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4. Peak Wavelength ( $\lambda_p$ ) Bin:

| Color | Bin Code | Spec. Range |
|-------|----------|-------------|
| IRP   | D        | 830-870 nm  |

5. Forward Voltage ( $V_F$ ) Bin:

| Color | Bin Code | Spec. Range |
|-------|----------|-------------|
| IRP   | D5       | 1.2-1.4 V   |
|       | D6       | 1.4-1.6 V   |
|       | E5       | 1.6-1.8 V   |
|       | E6       | 1.8-2.0 V   |

(It maintains a tolerance of  $\pm 0.1V$  on forward voltage measurements)

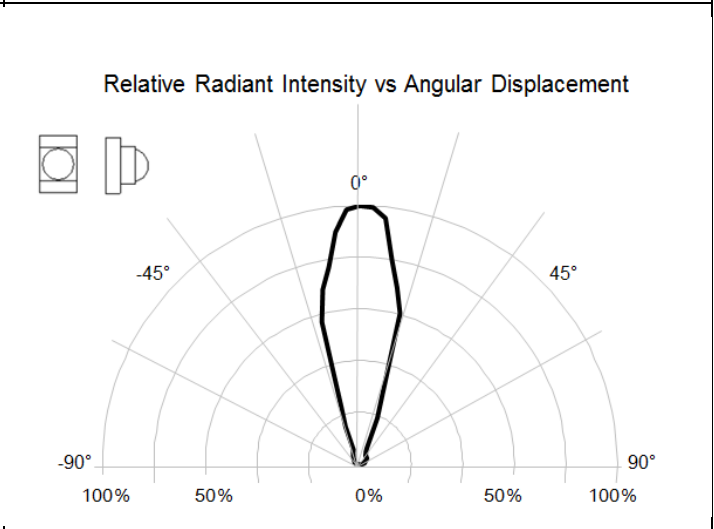
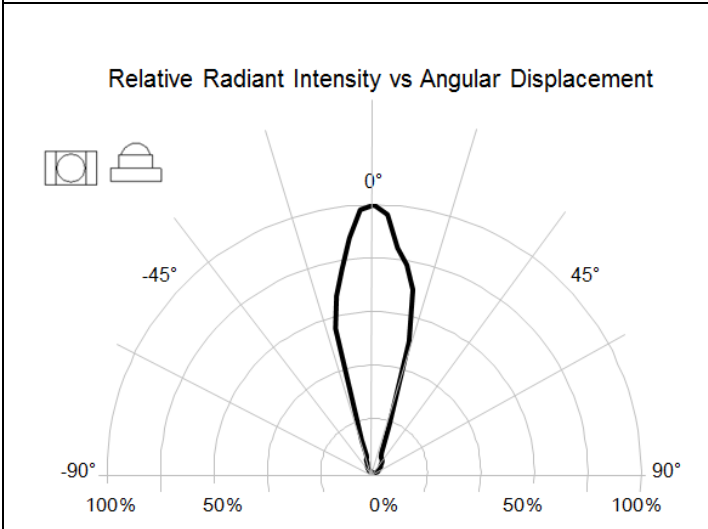
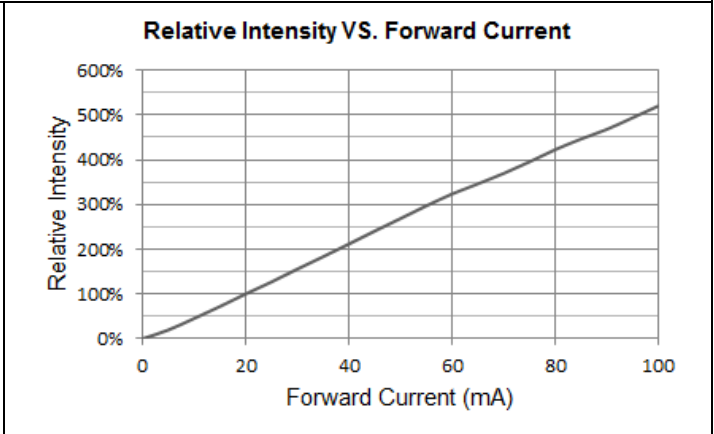
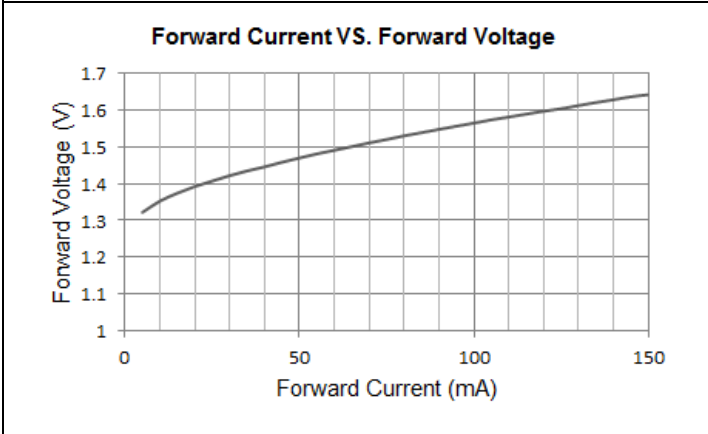
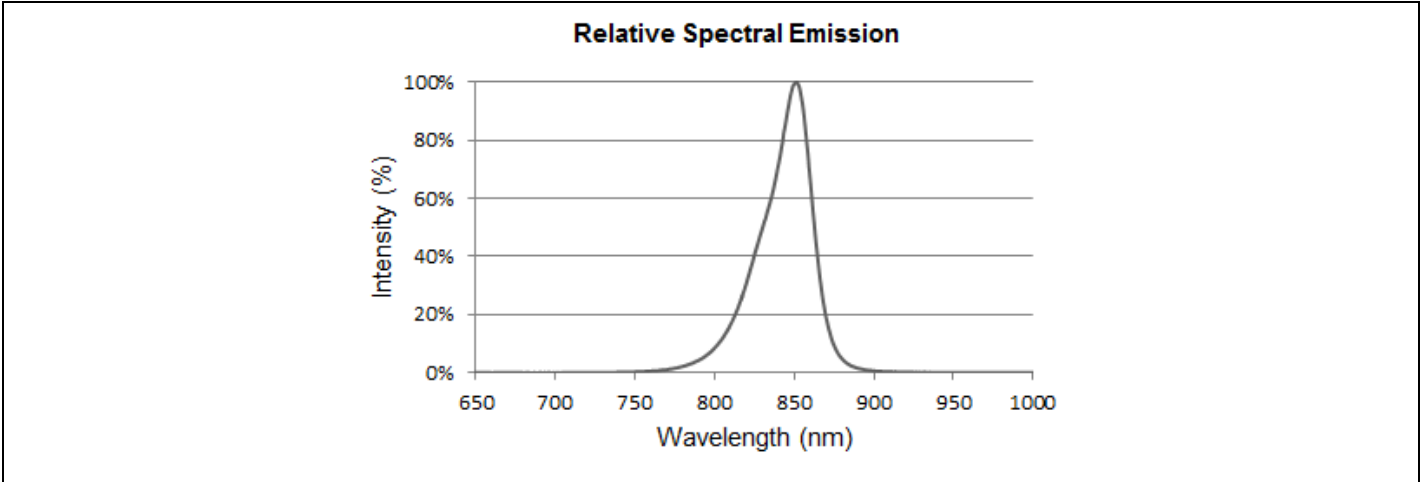
## Package Outline Dimension and Recommended Soldering Pattern for Reflow Soldering

(Unit:mm Tolerance: +/-0.1)

| Outline Dim.  | Soldering Pattern |
|---|-------------------|
|   |                   |
| <p>Soldering terminals may shift in the x, y direction.</p> |                   |

|   |                                     |             |           |
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**Characteristics of B2571IRP**



|   |                                     |             |           |
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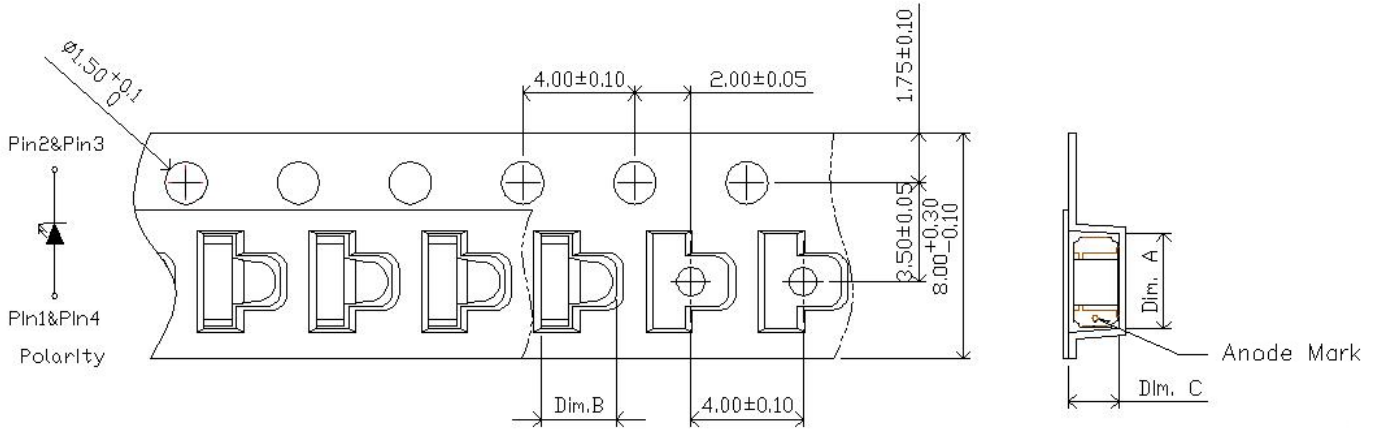
### Precaution for Use

1. The chips should not be used directly in any type of fluid such as water, oil, organic solvent, etc.
2. When the LEDs are illuminating, the maximum ambient temperature should be first considered before operation.
3. LEDs must be stored in a clean environment. A sealed container with a nitrogen atmosphere is necessary if the storage period is over 3 months after shipping.
4. The LEDs must be used within 4 weeks after unpacked. Unused products must be repacked in an anti-electrostatic package, folded to close any opening and then stored in a dry and cool space.
5. The appearance and specifications of the products may be modified for improvement without further notice.
6. The LEDs are sensitive to the static electricity and surge. It is strongly recommended to use a grounded wrist band and anti-electrostatic glove when handling the LEDs. If a voltage over the absolute maximum rating is applied to LEDs, it will damage LEDs. Damaged LEDs will show some abnormal characteristics such as remarkable increase of leak current, lower turn-on voltage and getting unlit at low current.

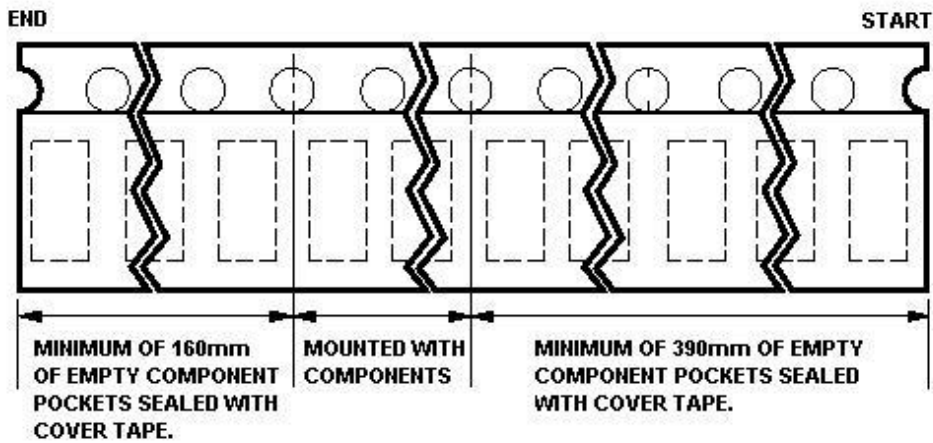
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**Packaging**  
**Tape Dimension**

**Side View**

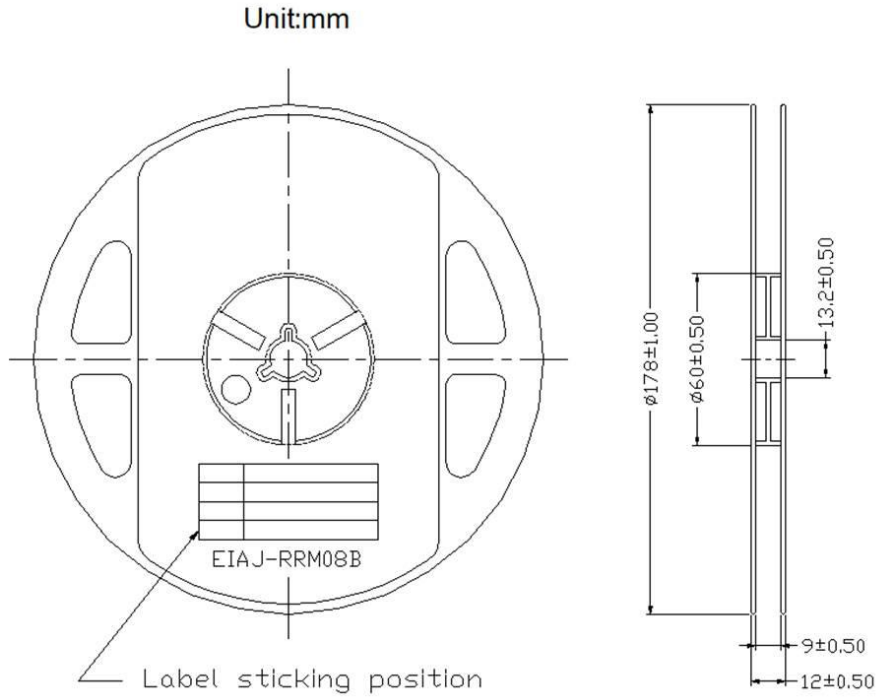


| Dim. A          | Dim. B          | Dim. C         | Q'ty/Reel |
|-----------------|-----------------|----------------|-----------|
| $3.30 \pm 0.10$ | $1.70 \pm 0.10$ | $2.2 \pm 0.10$ | 2K        |

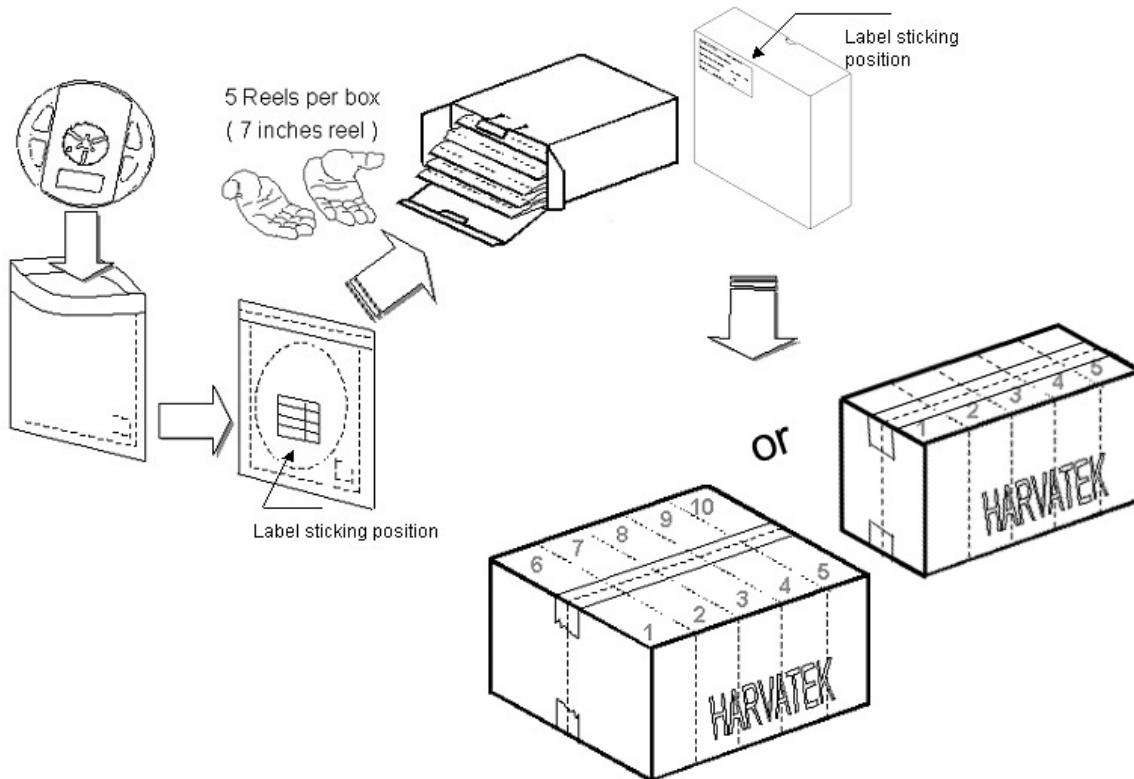


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## Reel Dimension



## Packing



|   |                                     |            |                        |
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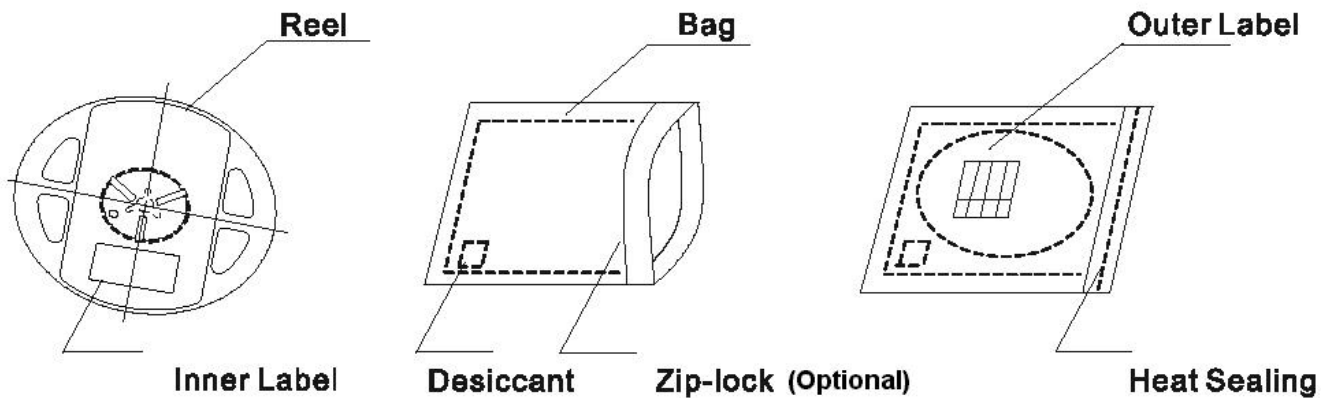
5 or 10 boxes per carton is available depending on shipment quantity.

### Dry Pack

All SMD optical devices are **MOISTURE SENSITIVE**. Avoid exposure to moisture at all times during transportation or storage. Every reel is packaged in a moisture protected anti-static bag. Each bag is properly sealed prior to shipment.

A humidity indicator will be included in the moisture protected anti-static bag prior to shipment.

The packaging sequence is as follows:



### Baking

Baking before soldering is recommended when the package has been unsealed for 4 weeks.

The conditions are as followings:

1. 60±3°C x(12~24hrs)and<5%RH, taped reel type.
2. 100±3°C x(45min~1hr), bulk type.
3. 130±3°C x(15min~30min), bulk type.

### Precautions

1. Avoid exposure to moisture at all times during transportation or storage.
2. Anti-Static precaution must be taken when handling GaN, InGaN, and AlInGaP products.
3. It is suggested to connect the unit with a current limiting resistor of the proper size. Avoid applying a reverse voltage beyond the specified limit.
4. Avoid operation beyond the limits as specified by the absolute maximum ratings.
5. Avoid direct contact with the surface through which the LED emits light.
6. If possible, assemble the unit in a clean room or dust-free environment.

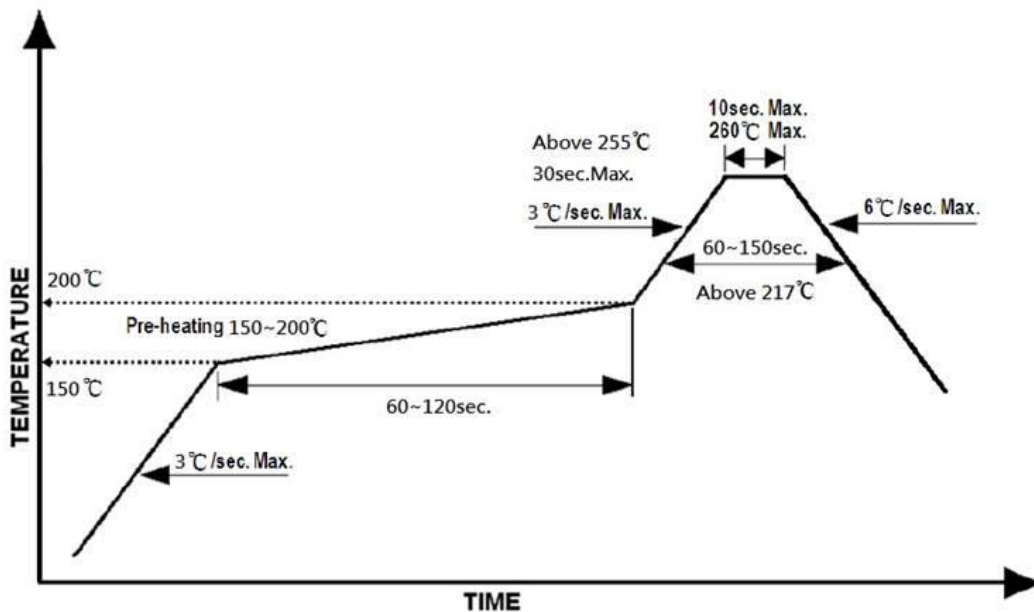
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**Reflow Soldering**

Recommend soldering paste specifications:

1. Operating temp.: Above 217 °C ,60~150 sec.
2. Peak temp.:260 °C Max.,10sec Max.
3. Reflow soldering should not be done more than two times.
4. Never attempt next process until the component is cooled down to room temperature after reflow.
5. The recommended reflow soldering profile (measured on the surface of the LED terminal) is as following:

Lead-free Solder Profile



**Reworking**

- Rework should be completed within 5 seconds under 260°C.
- The iron tip must not come in contact with the copper foil.
- Twin-head type is preferred.

**Cleaning**

Following are cleaning procedures after soldering:

- An alcohol-based solvent such as isopropyl alcohol (IPA) is recommended.
- Temperature x Time should be 50°C x 30sec. or <30°C x 3min
- Ultrasonic cleaning: < 15W/ bath; bath volume ≤ 1liter
- Curing: 100°C max, <3min

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